4 QUALITY EDUCATION

8 DECENT WORK AND ECONOMIC GROWTH

9 INDUSTRY, INNOVATION AND INFRASTRUCTURE

Training on Semiconductor Manufacturing Processes and Packaging Technologies

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Date：July 9-August 5, 2026

Application Deadline：June 5, 2026

Language：English, Español

Overview

This training introduces a comprehensive overview of the semiconductor industry value chain, including IC design, manufacturing processes, and packaging and testing, and incorporates circuit simulation and hands-on production line practice to help participants grasp key aspects from component fundamentals to practical application.

Course Arrangement

- Semiconductor Fundamentals and IC Design: Introduction to device principles, IC design concepts, and circuit simulation practice.
- Manufacturing and Packaging Practices: Overview of IC processes, packaging and testing, with hands-on simulation and production line exposure.
- Industry Visits: Site visits to key companies across the semiconductor supply chain.

Eligibility

- Applicants aged 20 or above with basic knowledge of electrical or electronic engineering and an interest in semiconductor applications.

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